

WE CLAIM:

1. A connection system suited for use with a fireproofed electronic device, the system comprising a heat conductive structure configured to transfer a communication signal and having a connection point that includes a heat sensitive material, wherein heat applied to the heat conductive structure modifies the heat sensitive material to thermally separate the heat conductive structure at the connection point.
2. The system of claim 1, further comprising a biasing member configured to apply a tension force at the connection point.
3. The system of claim 1, wherein the heat sensitive material is a low temperature solder.
4. The system of claim 1, wherein the heat conductive structure includes a co-axial cable.
5. The system of claim 1, wherein the heat conductive structure includes first and second wire members that are coupled together at the connecting point with the heat sensitive material.
6. The system of claim 5, wherein the first wire member is configured to extend through an exterior wall of a heat resistant container that houses the electronic device, and the second wire member is configured to be coupled to the electronic device stored in the heat resistant container.
7. A fireproof system for protecting a heat sensitive device, the system comprising:  
a heat resistant container having an internal chamber sized to house the heat sensitive device; and

a connection system including a heat conductive structure that extends from outside the heat resistant container into the internal chamber of the heat resistant container, the heat conductive structure being configured to transfer a communication signal from outside the heat resistant container to the heat sensitive device, the heat conductive structure having a connection point inside the internal chamber that includes a heat sensitive material;

whereby a heat source applied to the heat conductive structure modifies the heat sensitive material to thermally separate the heat sensitive device from the heat source.

8. The system of claim 7, further comprising a biasing member configured to apply a tension force to the heat conductive structure at the connection point.

9. The system of claim 7, wherein the heat resistant container includes an aperture extending between the interior and an exterior of the heat resistant container, the system further comprises a heat resistant feed-through member that extends through the aperture, and the first cable member extends through the heat resistant feed-through member.

10. The system of claim 7, wherein the heat sensitive device is a computer hardware device.

11. The system of claim 9, further comprising a heat resistant adhesive positioned within the heat resistant feed-through adjacent to the heat conductive wire.

12. The system of claim 7, wherein the heat resistant container comprises first and second housing members defining the internal chamber, the first and second housing members being sealed together with a heat resistant sealant.

13. The system of claim 7, wherein the heat resistant container includes a ceramic fiber and a binder material.

14. The system of claim 13, wherein the heat resistant container is formed using a vacuum molding, a compression molding, or a casting process.

15. The system of claim 7, wherein the heat conductive structure is molded into an exterior wall of the heat resistant container.

16. The system of claim 7, wherein the heat resistant container is a safe having locking and unlocking capabilities and heat resistant properties.

17. The system of claim 7, further comprising a safe having locking and unlocking capabilities and an interior cavity sized to receive the heat resistant container and the connection system.

18. The system of claim 7, further comprising a wireless communication system coupled to an exterior surface of the heat resistant container, wherein the heat conductive structure is coupled to the wireless communication system.

19. A method of protecting an electronic device from heat damage using a heat resistant container and a connection system, the connection system including a heat conductive structure having a heat sensitive member, the method comprising:

enclosing the electronic device in the heat resistant container;  
coupling the heat conductive structure to the electronic device;  
extending the heat conductive structure between an interior and an exterior of the heat resistant container; and

modifying the heat sensitive member when heat is applied to the heat conductive structure to thermally separate the heat conductive structure thereby protecting the electronic device from heat damage.

20. The method of claim 19, wherein the heat sensitive material is a low temperature solder, and modifying the heat sensitive material includes melting the low temperature solder.

21. The method of claim 19, further comprising fixing the heat conductive wire within an exterior wall of the heat resistant container.

22. The method of claim 19, wherein the system further comprises a biasing member and the method further includes applying a tension force to the heat conductive wire at the connection point with the biasing member.

23. The method of claim 22, wherein applying the tension force includes coupling the biasing member to the heat conductive wire and to the heat resistant container.

24. The method of claim 19, wherein the heat resistant container includes at least first and second housing members that define an interior cavity, and enclosing the electronic device includes sealing the first and second housing members together with a heat resistant adhesive.

25. The method of claim 19, wherein the heat resistant container is a safe having locking and unlocking capabilities.

26. The method of claim 25, wherein the safe includes a wireless communication system, and the method further comprises mounting the wireless communication system on an exterior surface of the safe and coupling the heat conductive wire to the wireless communication system and to the electronic device.

27. A method of protecting a heat sensitive device from heat damage using a heat resistant container and a connection system, the connection system including a heat conductive structure having a connection point, the method comprising:

enclosing the heat sensitive device in the heat resistant container;  
coupling the heat conductive structure to the heat sensitive device;  
extending the heat conductive structure between an interior and an exterior of the heat resistant container; and

thermally separating the heat conductive structure at the connection point when heat is applied to the heat conductive structure thereby protecting the heat sensitive device from heat damage.

28. The method of claim 27, wherein the system further comprises a biasing member and the method further includes applying a tension force to the heat conductive structure at the connection point with the biasing member.

29. The method of claim 28, wherein applying the tension force includes coupling the biasing member to the heat conductive structure.

30. The method of claim 27, enclosing the heat sensitive device includes mounting the heat sensitive device to the heat resistant container with a quick release mechanism.

31. The method of claim 27, wherein thermally separating the heat conductive structure includes physically separating the heat conductive structure at the connection point to disconnect the heat sensitive device from the source of the heat.